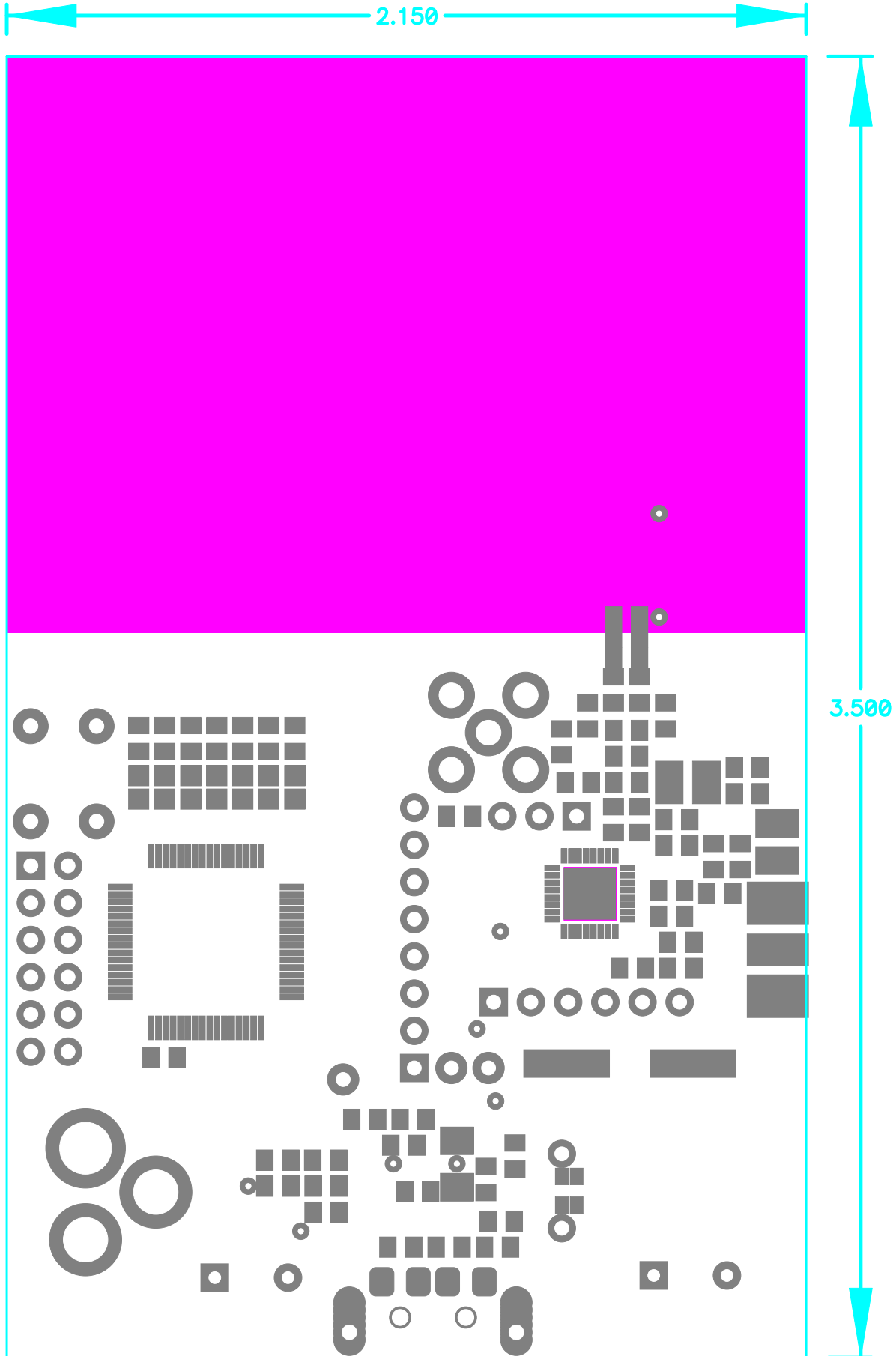
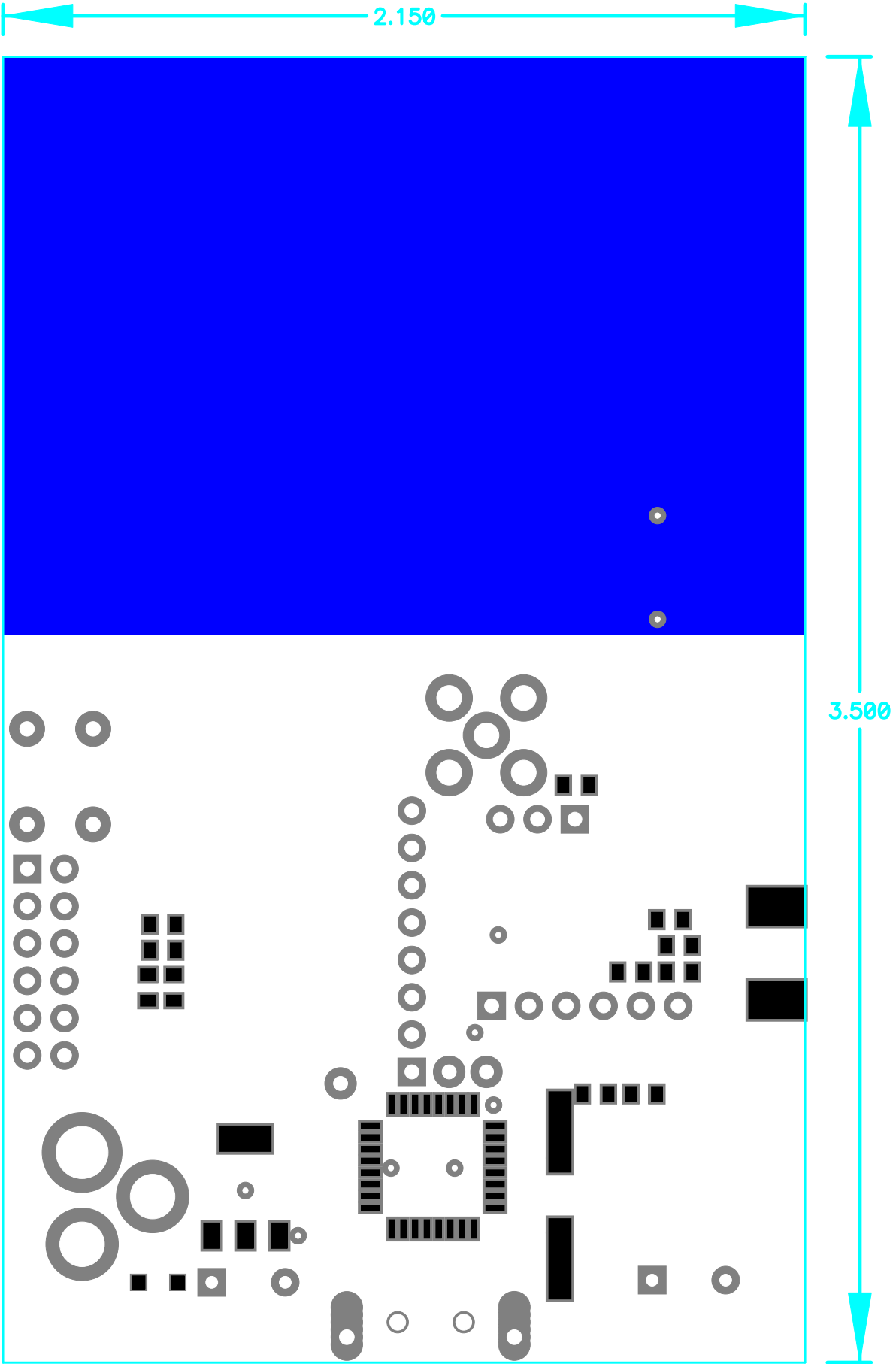
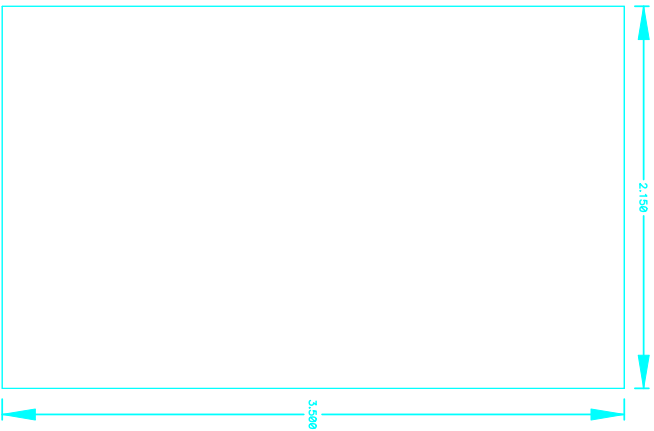






MATERIALS

- 1. ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND HAVE A FLAMMABILITY OF UL94V-0.
- 2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH LAYER STACK-UP
- 3. PLATING: TIN-LEAD
- 4. SOLDERMASK: SMOBC, LPI, IPC-SM-840, GREEN
- 5. SILKSCREEN: LPI WHITE
- 6. VENDOR'S IDENTIFICATION CODE: BOTTOM LAYER SILKSCREEN. IF ETCH USED INSTEAD, SHALL NOT COMPROMISE A GROUND PLANE.



FABRICATION

- 1. BOARDS ARE TO BE FABRICATED TO IPC-A-600, CLASS 2
- 2. BOARD DIMENSIONS ARE IN INCHES EXCEPT WHERE NOTED
- 3. ALL INTERNAL LAYERS ARE TO BE REGISTERED TO WITHIN 0.003 OF THE TRUE POSITION. THE MINIMUM DISTANCE FROM THE EDGE OF THE PLATED HOLE WALL IS TO BE NO CLOSER THAN 0.008 TO THE INTERNAL SHIELD
- 4. FINISHED LINE WIDTHS SHALL BE MAINTAINED TO WITHIN +/- 0.001 OF THE ARTWORK
- 5. DRILL SIZE HOLE DIAMETERS SHOWN (SEE TABLE) ARE FINISHED SIZES AFTER PLATING
- 6. HOLES REQUIRING PLATING, TO HAVE 0.001 (1 mil) MINIMUM THICKNESS COPPER
- 7. NET LIST TEST IS NOT REQUIRED

LAYER STACK-UP

- 1. 2 LAYER PCB
- 2. 2 OZ CU, BOTH SIDES
- 3. FINISHED BOARD THICKNESS, MEASURED COPPER TO COPPER, OF: 0.062 +0.003/-0.004

Drill Table			
Hole Dia (Inch)	Symbol	Quantity	Plated
0.008	+	552	Yes
0.015	X	9	Yes
0.032	Y	4	Yes
0.038	+	34	Yes
0.039	X	4	Yes
0.040	M	12	Yes
0.043	□	2	Yes
0.067	◇	5	Yes
0.120	⊠	2	Yes
0.140	◇	1	Yes



Texas Instruments, Inc.

TRF7960 EVM

